**IN THE CLAIMS**

1. A component polishing method, comprising:

polishing a component; and

protecting at least a portion of the component during the polishing using a sacrificial mask, wherein at least some of the sacrificial mask is removed during the polishing, and a thickness of the sacrificial mask prior to polishing is greater than a thickness of the sacrificial mask after some polishing.

2. The component polishing method of claim 1, wherein the sacrificial mask comprises wax.

3. The component polishing method of claim 1, wherein the sacrificial mask is secured directly to the portion of the component.

4. The component polishing method of claim 1, wherein the sacrificial mask is removed entirely from the component during the polishing .

5. The component polishing method of claim 1, wherein some of the sacrificial mask remains secured to the portion of the component after the polishing and some of the sacrificial mask is removed entirely from the component during the polishing to expose a portion of the component that was previously covered by some of the sacrificial mask.

6. The component polishing method of claim 1, wherein the component is an airfoil and the portion comprises a leading edge or a trailing edge of the airfoil.

7. The component polishing method of claim 1, wherein the polishing comprises vibratory polishing the component using a media, and the sacrificial mask limits contact between the media and the portion of the component.

8. The component polishing method of claim 1, including dipping the portion of the component in a liquid before the polishing, the liquid hardening to form the sacrificial mask.

9. The component polishing method of claim 8, wherein the liquid comprises a paraffin wax.

10. The component polishing method of claim 1, including removing some of the sacrificial mask using media during a vibratory polishing of the component.